



LYCHEE Flight Computer

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.6062 mm
Board overall dimensions:	80.0000 mm x 80.0000 mm	Min hole diameter:	0.3000 mm
Min track/spacing:	0.1500 mm / 0.1250 mm	Impedance Control:	No
Copper Finish:	HAL SnPb	Plated Board Edge:	No
Castellated pads:	No		
Edge card connectors:	No		



Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Blue	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.2104 mm		4.5	0.02
In1.Cu	copper		0.0152 mm		1	0
Dielectric 2	core	FR4	1.065 mm		4.5	0.02
In2.Cu	copper		0.0152 mm		1	0
Dielectric 3	prepreg	FR4	0.2104 mm		4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Blue	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

Drawn By H. Franks
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Sheet: Assembly
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Title: Lychee Flight Computer

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KiCad E.D.A. pcbnew (6.0.6)

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